

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6084181

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| YUSHENG LIN | 04/16/2020 |
| MICHAEL J. SEDDON | 04/16/2020 |
| FRANCIS J. CARNEY | 04/16/2020 |
| TAKASHI NOMA | 04/20/2020 |
| EIJI KUROSE | 04/16/2020 |
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| City: | PHOENIX |
| State/Country: | ARIZONA |
| Postal Code: | 85008 |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 16861910 |
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| ATTORNEY DOCKET NUMBER: | ONS02401P03US |
| NAME OF SUBMITTER: | KELLY A. HALL |
| SIGNATURE: | /Kelly A. Hall/ |
| DATE SIGNED: | 04/29/2020 |
| Total Attachments: 7 | |

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For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we,

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| Francis J. CARNEY | Mesa, Arizona, U.S.A. |
| Takashi NOMA | Ota, Japan |
| Eiji KUROSE | Oizumi-machi, Japan |

agree to sell, assign, and transfer, and do hereby sell, assign, and transfer to Semiconductor Components Industries, LLC, a limited liability company of the State of Delaware, having its principal office in Phoenix, State of Arizona, United States of America, and its successors, assigns, and legal representatives ("SCI"), the entire right, title, and interest in and to the inventions and discoveries as described, illustrated, and/or claimed in

Title: SEMICONDUCTOR PACKAGE ELECTRICAL CONTACTS AND RELATED METHODS

Attorney Docket No.: ONS02401P03US

Serial No.: US 16/861,910

Filing Date: April 29, 2020

together with the entire right, title, and interest in and to the above listed application(s), and in and to any and all provisional, non-provisional, divisional, continuation, continuation-in-part, international, foreign, and any and all other applications related thereto, and also including any and all grants, issuances, letters patent, reissues, reexaminations, renewals, priority rights, and priority claims related to any of the foregoing, and any and all rights to collect past damages for infringement of any of the foregoing (the "Patent Rights").

We further authorize SCI to apply for and hold and maintain the Patent Rights throughout the world directly in its own name or any other name which SCI deems appropriate in its sole discretion, and to claim the priority of the filing date of the above listed application(s).

適正・相当な対価を受領しており、それが十分な対価であることを認めた上で、我々こと

| (市及び州又は国) | の(氏名) |
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所有権: SEMICONDUCTOR PACKAGE ELECTRICAL CONTACTS AND RELATED METHODS

代理人明細書番号: ONS02401P03US

シリアル番号: US 16/861,910

申請日: April 29, 2020

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By (Inventor signature):

Yusheng LIN

Signed on this

day

16

day of

month

April

2020

year

PATENT

REEL: 052527 FRAME: 0451

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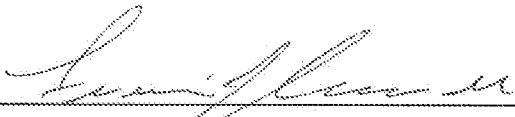
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By (Inventor signature): 
Michael J. SEDDON

Signed on this 16 day of April, 2020
day month year

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ONS02401P03US

By (Inventor signature): 
Francis J. CARNEY

Signed on this 16 day of April, 2020
day month year

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ON502401P03U5

By (Inventor signature):
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Takashi NOMA

認証日:

20th April 2020

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By (Inventor signature):

署名欄 (発明者の署名):

Eiji KUROSE

Eiji Kurose

認証日:

April 16th 2020